IMAPS 2011 Program Outline

Time	3D Packaging Track	Modeling, Design and Reliability Track	Next Generation Materials Track	Assembly and Packaging Track	Advanced Technologies Track	Focus Track: Advanced Packaging & System-Integration	Interactive Track
Sunday, October 9							
1:00 pm-5:00 pm	Professional Development Courses (**HALF-DAY COURSES ONLY**)						
5:00 pm-6:00 pm	Professional Development Course Reception (Registrants and Instructors Only)						
Monday, October 10							
9:00 am-5:00 pm *(unless otherwise noted)*	Professional Development Courses (**FULL AND HALF-DAY COURSES**)						
5:00 pm-7:30 pm	Welcome Reception (**ALL ARE INVITED**)						
Tuesday, October 11							
8:00 am-11:10 am	3D - TSV Processes and Materials	Electrical Modeling, Signal and Power Integrity	Advanced Materials		LED Packaging	European Perspectives on Packaging & System-Integration I	
11:00 am-5:30 pm	Exhibits Hall Open						
11:25 am-11:40 am	Annual Business Meeting						
11:40 am-12:00 pm	Awards Ceremony						
12:00 pm-12:45 pm	Keynote Presentation: Mr. Liam Madden, Corporate Vice President, Xilinx, Inc.						
12:50 pm-1:50 pm	Lunch Kiosks (Food available for purchase)						
1:55 pm-5:40 pm	3D TSV Interposers	Design for Reliability	High Performance Interconnects and Boards	Pb-Free Solder Materials and RoHS, Processes and Reliability	Emerging Technologies	European Perspectives on Packaging & System-Integration II	
Wednesday, October 12							
8:00 am-11:40 am	3D Packaging and Applications	Materials, Process and Reliability	Ceramic and LTCC Packaging I	Wire Bonding and Stud Bumping	MEMS Packaging	Advanced Packaging in China (Chinese-to-English Translated)	
9:00 am-5:30 pm	Exhibits Hall Open						
11:45 am-12:30 pm	Keynote Presentation: TBD						
12:30 pm-1:30 pm	Lunch in the Exhibits Hall						
1:35 pm-5:25 pm	3D Packaging, Thermal/Mechanical Simulation and Modeling	Package Reliability Testing	Ceramic and LTCC Packaging II	Substrate Materials and Technologies for the Semiconductor and Solar Industries		Improvements in Advanced Packaging from Japan (Japanese-to-English Translated)	Interactive Forum (Poster Session)
5:30 pm-6:30 pm	Global Business Council (GBC) Marketing Forum **(INCLUDED WITH YOUR FULL SYMPOSIUM REGISTRATION)**						
6:30 pm-7:30 pm	GBC Networking Reception						
Thursday, October 13							
8:00 am-12:00 pm		Microwave and RF Applications	Thermal Management	Flip Chip and Wafer Bumping: Processes and Reliability	Printed Electronics and Additive Manufacturing	Optoelectronics and Photonics Packaging / Wafer-Level Integration & System Packaging	
9:00 am-12:00 pm	Exhibits Hall Open						
9:00 am-12:00 pm	IMAPS 2012 Booth Selection in the Exhibit Hall						

A SPECIAL THANKS
TO THE
TECHNICAL COMMITTEES,
SESSION CHAIRS, SPEAKERS AND
SPONSORS!